

Multilayer Ceramic Chip Capacitors

C3225X7R1H335K250AB



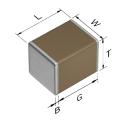






TDK item description C3225X7R1H335KT****

Applications	Commercial Grade Please refer to Part No. <u>CGA6P3X7R1H335K250AB</u> for Automotive use.	
Feature	General (Up to 75V)	
Series	C3225 [EIA 1210]	
Status	Production (Not Recommended for New Design)	



	Size	
Length(L)	3.20mm ±0.40mm	
Width(W)	2.50mm ±0.30mm	
Thickness(T)	2.50mm ±0.30mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)		
Recommended Land Pattern (PA)	2.00mm to 2.40mm	
Recommended Land Pattern (PB)	1.00mm to 1.20mm	
Recommended Land Pattern (PC)	1.90mm to 2.50mm	

Electrical Characteristics		
Capacitance	3.3μF ±10%	
Rated Voltage	50VDC	
Temperature Characteristic	X7R(±15%)	
Dissipation Factor (Max.)	5%	
Insulation Resistance (Min.)	151ΜΩ	

Other		
Soldering Method	Reflow	
AEC-Q200	No	
Packing	Blister (Plastic)Taping [180mm Reel]	
Package Quantity	1000pcs	

[!] Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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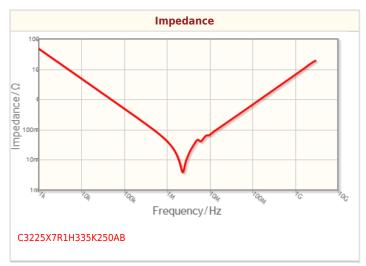


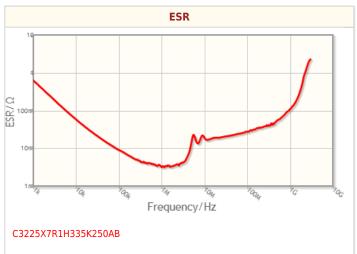


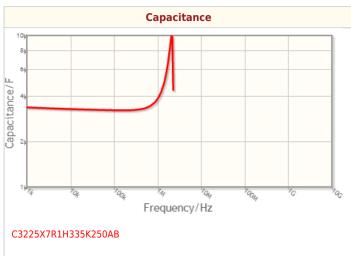


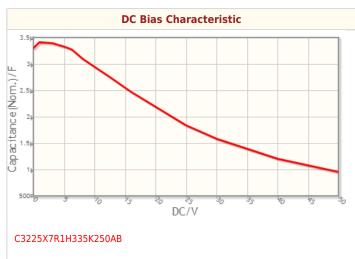


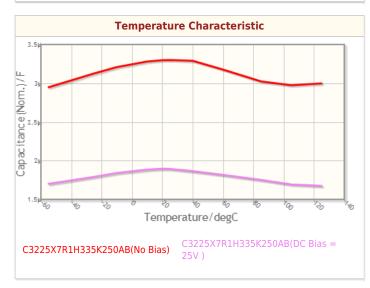
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

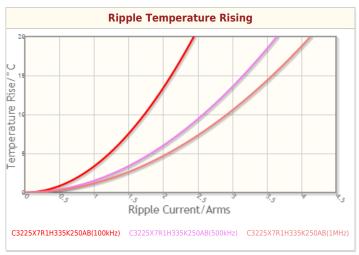












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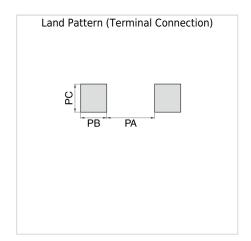








Associated Images



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